

ABSOLUTE MAXIMUM RATINGS (Note 1)

Supply Voltage		TS Voltage (100ms)	–5V to 80V
V_{CC}	–0.3V to 15V	Peak Output Current < 1 μ s (TG)	4A
BOOST – TS	–0.3V to 15V	Operating Ambient Temperature Range	
INP Voltage	–0.3V to 15V	(Note 2)	–40°C to 85°C
BOOST Voltage (Continuous)	–0.3V to 85V	Junction Temperature (Note 3)	125°C
BOOST Voltage (100ms)	–0.3V to 95V	Storage Temperature Range	–65°C to 150°C
TS Voltage (Continuous)	–5V to 70V	Lead Temperature (Soldering, 10 sec)	300°C

PIN CONFIGURATION

<p>TOP VIEW</p> <p>MS8E PACKAGE 8-LEAD PLASTIC MSOP $T_{JMAX} = 125^{\circ}\text{C}$, $\theta_{JA} = 40^{\circ}\text{C/W}$ EXPOSED PAD (PIN 9) IS GND, MUST BE SOLDERED TO PCB</p>	<p>TOP VIEW</p> <p>S6 PACKAGE 6-LEAD PLASTIC SOT-23 $T_{JMAX} = 125^{\circ}\text{C}$, $\theta_{JA} = 230^{\circ}\text{C/W}$</p>
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ORDER INFORMATION

LEAD FREE FINISH	TAPE AND REEL	PART MARKING	PACKAGE DESCRIPTION	TEMPERATURE RANGE
LTC4440EMS8E-5#PBF	LTC4440EMS8E-5#TRPBF	LTBRG	8-Lead Plastic MSOP	–40°C to 85°C
LTC4440ES6-5#PBF	LTC4440ES6-5#TRPBF	LTBRF	6-Lead Plastic SOT-23	–40°C to 85°C

Consult LTC Marketing for parts specified with wider operating temperature ranges.

Consult LTC Marketing for information on nonstandard lead based finish parts.

For more information on lead free part marking, go to: <http://www.linear.com/leadfree/>

For more information on tape and reel specifications, go to: <http://www.linear.com/tapeandreel/>

ELECTRICAL CHARACTERISTICS

The ● denotes specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^{\circ}\text{C}$. $V_{CC} = V_{BOOST} = 6\text{V}$, $V_{TS} = \text{GND} = 0\text{V}$, unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Main Supply (V_{CC})						
I_{VCC}	DC Supply Current Normal Operation UVLO	INP = 0V $V_{CC} < \text{UVLO Threshold (Falling)} - 0.1\text{V}$		200 18	325 40	μA
UVLO	Undervoltage Lockout Threshold	V_{CC} Rising V_{CC} Falling Hysteresis	● 2.75 ● 2.60	3.20 3.04	3.65 3.50	V mV
Bootstrapped Supply (BOOST – TS)						
I_{BOOST}	DC Supply Current Normal Operation	INP = 0V INP = 6V		0 310	450	μA

ELECTRICAL CHARACTERISTICS

The ● denotes specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_{CC} = V_{BOOST} = 6\text{V}$, $V_{TS} = 0\text{V}$, unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Input Signal (INP)							
V_{IH}	High Input Threshold	INP Ramping High	●	1.2	1.6	2	V
V_{IL}	Low Input Threshold	INP Ramping Low	●	0.8	1.25	1.6	V
$V_{IH} - V_{IL}$	Input Voltage Hysteresis				0.350		V
I_{INP}	Input Pin Bias Current				± 0.01	± 2	μA
Output Gate Driver (TG)							
V_{OH}	High Output Voltage	$I_{TG} = -10\text{mA}$, $V_{OH} = V_{BOOST} - V_{TG}$			0.7		V
V_{OL}	Low Output Voltage	$I_{TG} = 100\text{mA}$	●		185	275	mV
I_{PU}	Peak Pull-Up Current		●	0.75	1.1		A
R_{DS}	Output Pull-Down Resistance		●		1.85	2.75	Ω
Switching Timing							
t_r	Output Rise Time	10% – 90%, $C_L = 1\text{nF}$ 10% – 90%, $C_L = 10\text{nF}$			10 100		ns ns
t_f	Output Fall Time	10% – 90%, $C_L = 1\text{nF}$ 10% – 90%, $C_L = 10\text{nF}$			7 70		ns ns
t_{PLH}	Output Low-High Propagation Delay		●		35	65	ns
t_{PHL}	Output High-Low Propagation Delay		●		33	65	ns

Note 1: Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.

Note 2: The LTC4440-5 is guaranteed to meet performance specifications from 0°C to 85°C . Specifications over the -40°C to 85°C operating temperature range are assured by design, characterization and correlation with statistical process controls.

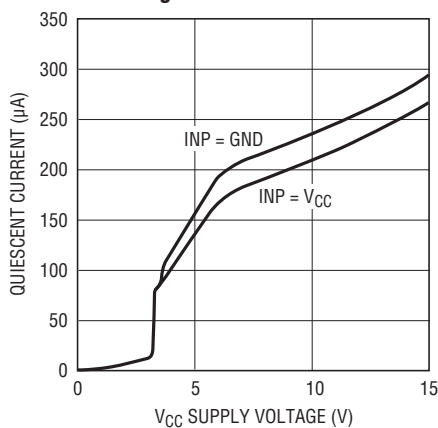
Note 3: T_J is calculated from the ambient temperature T_A and power dissipation PD according to the following formula:

$$T_J = T_A + (PD \cdot \theta_{JA}^\circ\text{C/W})$$

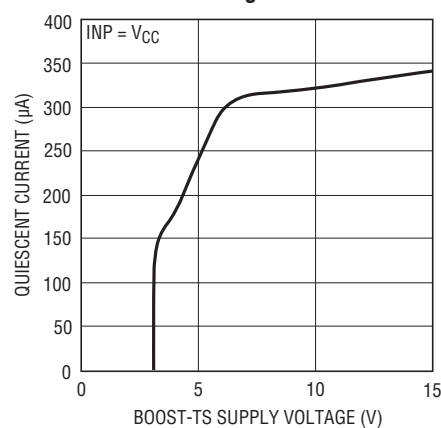
Note 4: Failure to solder the exposed back side of the MS8E package to the PC board will result in a thermal resistance much higher than 40°C/W .

TYPICAL PERFORMANCE CHARACTERISTICS

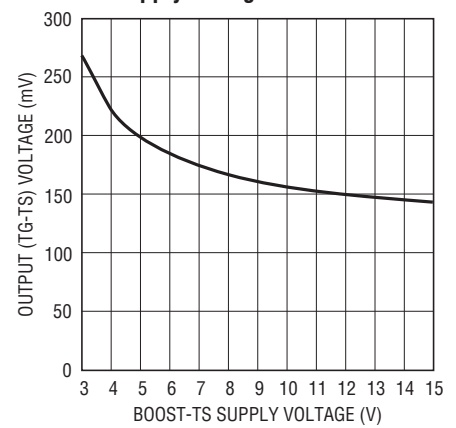
V_{CC} Supply Quiescent Current vs Voltage



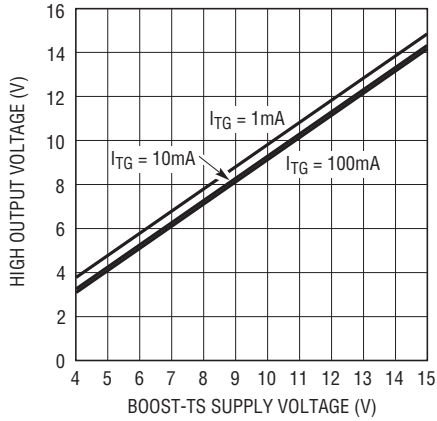
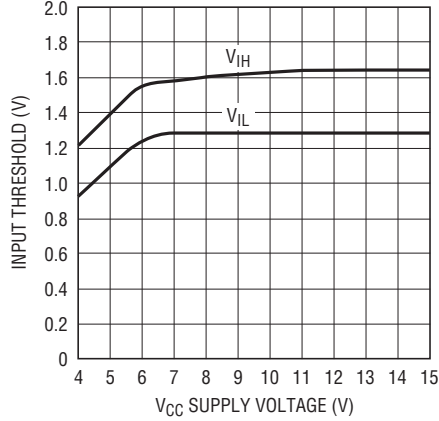
BOOST-TS Supply Quiescent Current vs Voltage



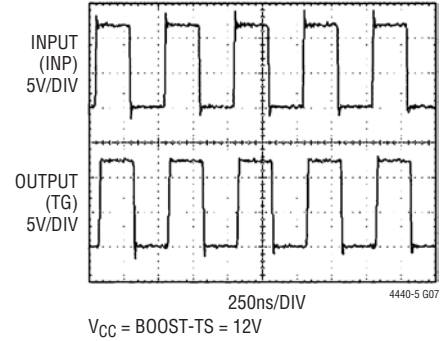
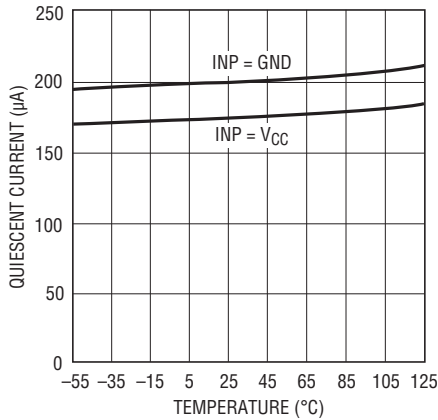
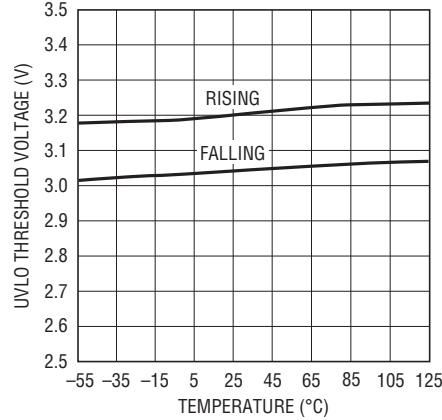
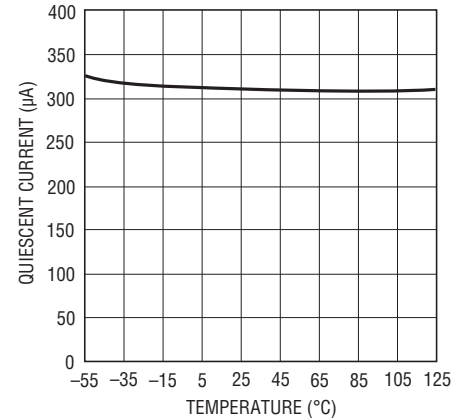
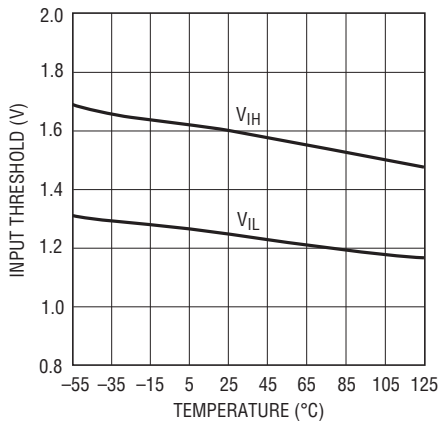
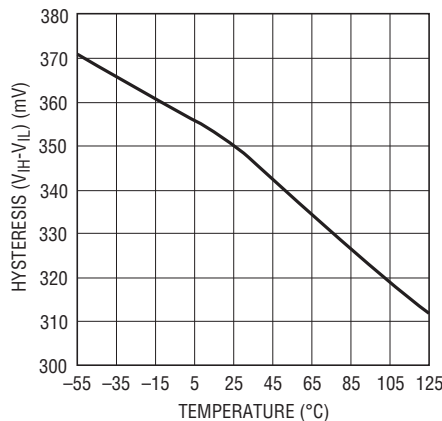
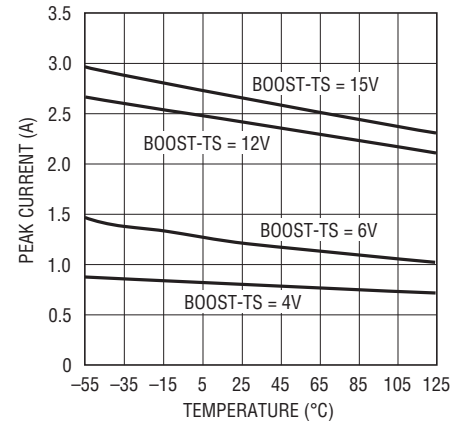
Output Low Voltage (V_{OL}) vs Supply Voltage



TYPICAL PERFORMANCE CHARACTERISTICS

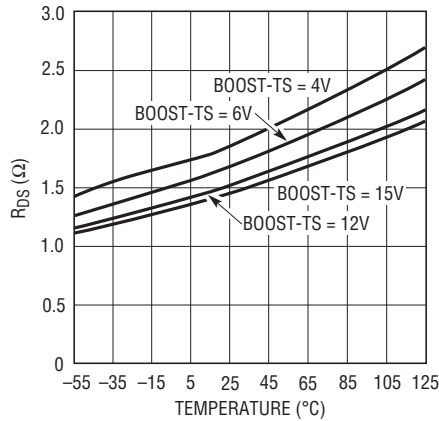
Output High Voltage (V_{OH})
vs Supply VoltageInput (INP) Thresholds
vs Supply Voltage

2MHz Operation

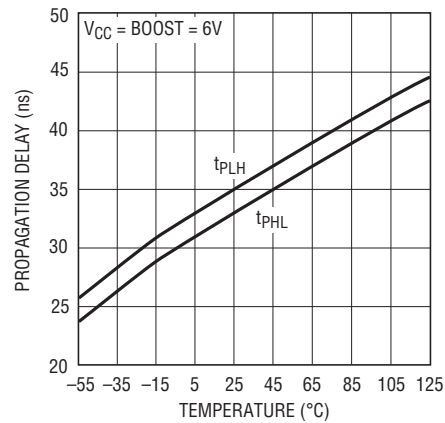
 V_{CC} Supply Current
vs Temperature V_{CC} Undervoltage Lockout
Thresholds vs TemperatureBOOST-TS Quiescent Current
vs TemperatureInput (INP) Threshold
vs TemperatureInput Threshold Hysteresis
vs TemperaturePeak Driver (TG) Pull-Up Current
vs Temperature

TYPICAL PERFORMANCE CHARACTERISTICS

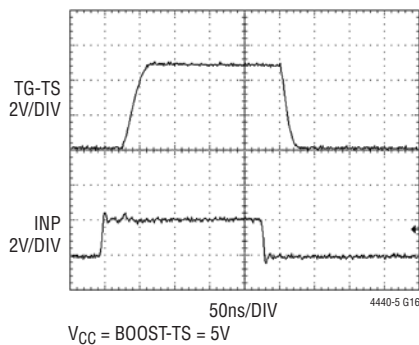
Output Driver Pull-Down Resistance vs Temperature



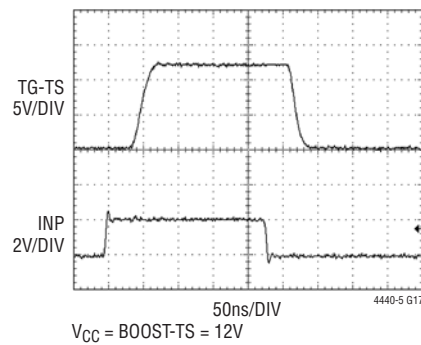
Propagation Delay vs Temperature



Driving a 3300pF Capacitive Load



Driving a 3300pF Capacitive Load



PIN FUNCTIONS

SOT-23 Package

V_{CC} (Pin 1): Chip Supply. This pin powers the internal low side circuitry. A low ESR ceramic bypass capacitor should be tied between this pin and the GND pin (Pin 2).

GND (Pin 2): Chip Ground.

INP (Pin 3): Input Signal. TTL/CMOS compatible input referenced to GND (Pin 2).

TS (Pin 4): Top (High Side) source connection or GND if used in ground referenced applications.

TG (Pin 5): High Current Gate Driver Output (Top Gate). This pin swings between TS and BOOST.

BOOST (Pin 6): High Side Bootstrapped Supply. An external capacitor should be tied between this pin and TS (Pin 4). Normally, a bootstrap diode is connected between V_{CC} (Pin 1) and this pin. Voltage swing at this pin is from V_{CC} - V_D to V_{IN} + V_{CC} - V_D, where V_D is the forward voltage drop of the bootstrap diode.

PIN FUNCTIONS

Exposed Pad MS8E Package

INP (Pin 1): Input Signal. TTL/CMOS compatible input referenced to GND (Pin 2).

GND (Pins 2, 4): Chip Ground.

V_{CC} (Pin 3): Chip Supply. This pin powers the internal low side circuitry. A low ESR ceramic bypass capacitor should be tied between this pin and the GND pin (Pin 2).

NC (Pin 5): No Connect. No connection required. For convenience, this pin may be tied to Pin 6 (BOOST) on the application board.

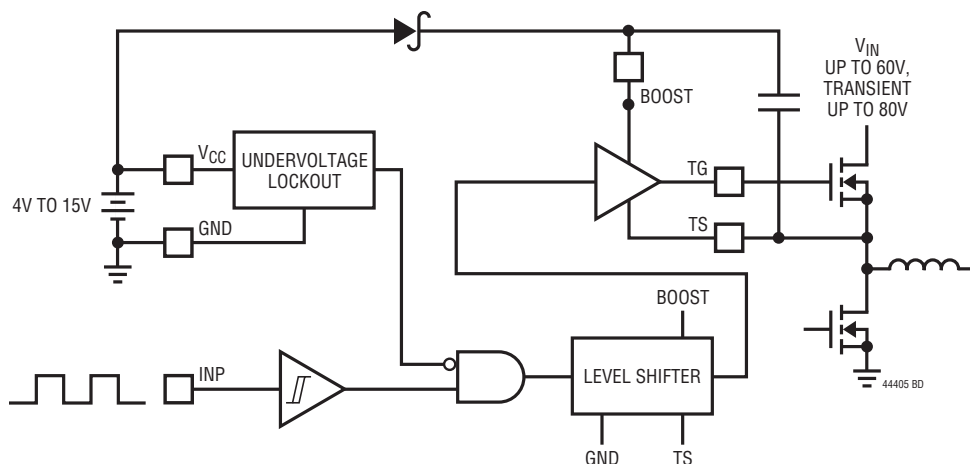
BOOST (Pin 6): High Side Bootstrapped Supply. An external capacitor should be tied between this pin and TS (Pin 8). Normally, a bootstrap diode is connected between V_{CC} (Pin 3) and this pin. Voltage swing at this pin is from V_{CC} – V_D to V_{IN} + V_{CC} – V_D, where V_D is the forward voltage drop of the bootstrap diode.

TG (Pin 7): High Current Gate Driver Output (Top Gate). This pin swings between TS and BOOST.

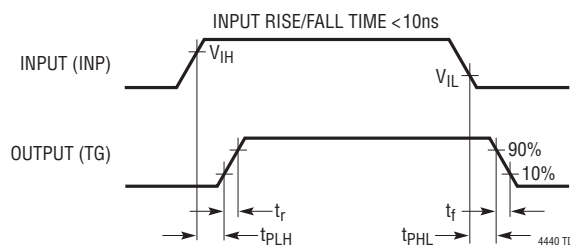
TS (Pin 8): Top (High Side) source connection or GND if used in ground referenced applications.

Exposed Pad (Pin 9): Ground. Must be electrically connected to Pins 2 and 4 and soldered to PCB ground for optimum thermal performance.

BLOCK DIAGRAM



TIMING DIAGRAM



APPLICATIONS INFORMATION

Overview

The LTC4440-5 receives a ground-referenced, low voltage digital input signal to drive a high side N-channel power MOSFET whose drain can float up to 80V above ground, eliminating the need for a transformer between the low voltage control signal and the high side gate driver. The LTC4440-5 normally operates in applications with input supply voltages (V_{IN}) up to 60V, but is able to withstand and continue to function during 80V, 100ms transients on the input supply.

The powerful output driver of the LTC4440-5 reduces the switching losses of the power MOSFET, which increase with transition time. The LTC4440-5 is capable of driving a 1nF load with 10ns rise and 7ns fall times using a bootstrapped supply voltage $V_{BOOST-TS}$ of 6V.

Input Stage

The LTC4440-5 employs TTL/CMOS compatible input logic level or thresholds that allow a low voltage digital signal to drive standard threshold power MOSFETs. The LTC4440-5 contains an internal voltage regulator that biases the input buffer, allowing the input thresholds ($V_{IH} = 1.6V$, $V_{IL} = 1.25V$) to be relatively independent of variations in V_{CC} . The 350mV hysteresis between V_{IH} and V_{IL} eliminates false triggering due to noise during switching transitions. However, care should be taken to keep this pin from any noise pickup, especially in high frequency, high voltage applications. The LTC4440-5 input buffer has a high input impedance and draws negligible input current, simplifying the drive circuitry required for the input.

Output Stage

A simplified version of the LTC4440-5's output stage is shown in Figure 1. The pull-down device is an N-channel MOSFET (N1) and the pull-up device is an NPN bipolar junction transistor (Q1). The output swings from the lower rail (TS) to within an NPN V_{BE} (~0.7V) of the positive rail (BOOST). This large voltage swing is important in driving external power MOSFETs, whose $R_{DS(on)}$ is inversely proportional to its gate overdrive voltage ($V_{GS} - V_{TH}$).

The LTC4440-5's peak pull-up (Q1) current is 1.1A while the pull-down (N1) resistance is 1.85 Ω , with a BOOST-TS supply of 6V. The low impedance of N1 is required to

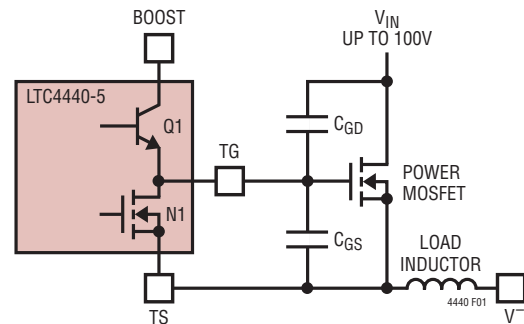


Figure 1. Capacitance Seen by TG During Switching

discharge the power MOSFET's gate capacitance during high-to-low signal transitions. When the power MOSFET's gate is pulled low (gate shorted to source through N1) by the LTC4440-5, its source (TS) is pulled low by its load (e.g., an inductor or resistor). The slew rate of the source/gate voltage causes current to flow back to the MOSFET's gate through the gate-to-drain capacitance (C_{GD}). If the MOSFET driver does not have sufficient sink current capability (low output impedance), the current through the power MOSFET's C_{GD} can momentarily pull the gate high, turning the MOSFET back on.

A similar scenario exists when the LTC4440-5 is used to drive a low side MOSFET. When the low side power MOSFET's gate is pulled low by the LTC4440-5, its drain voltage is pulled high by its load (e.g., inductor or resistor). The slew rate of the drain voltage causes current to flow back to the MOSFET's gate through its gate-to-drain capacitance. If the MOSFET driver does not have sufficient sink current capability (low output impedance), the current through the power MOSFET's C_{GD} can momentarily pull the gate high, turning the MOSFET back on.

Rise/Fall Time

Since the power MOSFET generally accounts for the majority of the power loss in a converter, it is important to quickly turn it on or off, thereby minimizing the transition time in its linear region. The LTC4440-5 can drive a 1nF load with a 10ns rise time and 7ns fall time.

The LTC4440-5's rise and fall times are determined by the peak current capabilities of Q1 and N1. The predriver that drives Q1 and N1 uses a nonoverlapping transition scheme to minimize cross-conduction currents. N1 is fully turned off before Q1 is turned on and vice versa.

44405fb

APPLICATIONS INFORMATION

Power Dissipation

To ensure proper operation and long-term reliability, the LTC4440-5 must not operate beyond its maximum temperature rating. Package junction temperature can be calculated by:

$$T_J = T_A + PD (\theta_{JA})$$

where:

T_J = Junction Temperature

T_A = Ambient Temperature

PD = Power Dissipation

θ_{JA} = Junction-to-Ambient Thermal Resistance

Power dissipation consists of standby and switching power losses:

$$PD = P_{STDBY} + P_{AC}$$

where:

P_{STDBY} = Standby Power Losses

P_{AC} = AC Switching Losses

The LTC4440-5 consumes very little current during standby. The DC power loss at $V_{CC} = 6V$ and $V_{BOOST-TS} = 6V$ is only $(200\mu A)(6V) = 1.2mW$ with $INP = 0V$.

AC switching losses are made up of the output capacitive load losses and the transition state losses. The capacitive load losses are primarily due to the large AC currents needed to charge and discharge the load capacitance during switching. Load losses for the output driver driving a pure capacitive load C_{OUT} would be:

$$\text{Load Capacitive Power} = (C_{OUT})(f)(V_{BOOST-TS})^2$$

The power MOSFET's gate capacitance seen by the driver output varies with its V_{GS} voltage level during switching. A power MOSFET's capacitive load power dissipation can be calculated using its gate charge, Q_G . The Q_G value corresponding to the MOSFET's V_{GS} value (V_{CC} in this case) can be readily obtained from the manufacturer's Q_G vs V_{GS} curves:

$$\text{Load Capacitive Power (MOS)} = (V_{BOOST-TS})(Q_G)(f)$$

Transition state power losses are due to both AC currents required to charge and discharge the driver's internal

nodal capacitances and cross-conduction currents in the internal gates.

Undervoltage Lockout (UVLO)

The LTC4440-5 contains an undervoltage lockout detector that monitors V_{CC} . When V_{CC} falls below 3.04V, the internal buffer is disabled and the output pin TG is pulled down to TS.

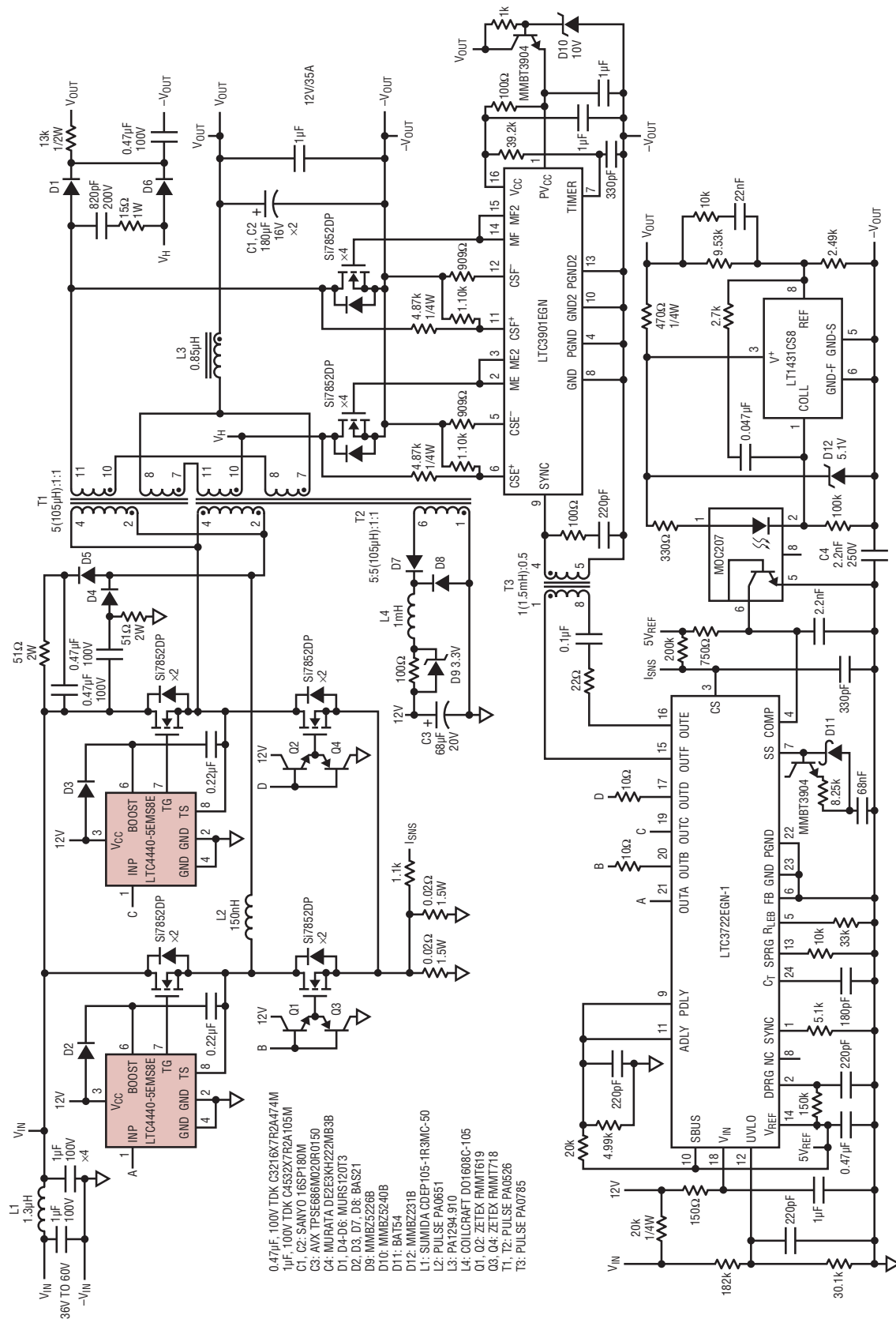
Bypassing and Grounding

The LTC4440-5 requires proper bypassing on the V_{CC} and $V_{BOOST-TS}$ supplies due to its high speed switching (nanoseconds) and large AC currents (Amperes). Careless component placement and PCB trace routing may cause excessive ringing and under/overshoot.

To obtain the optimum performance from the LTC4440-5:

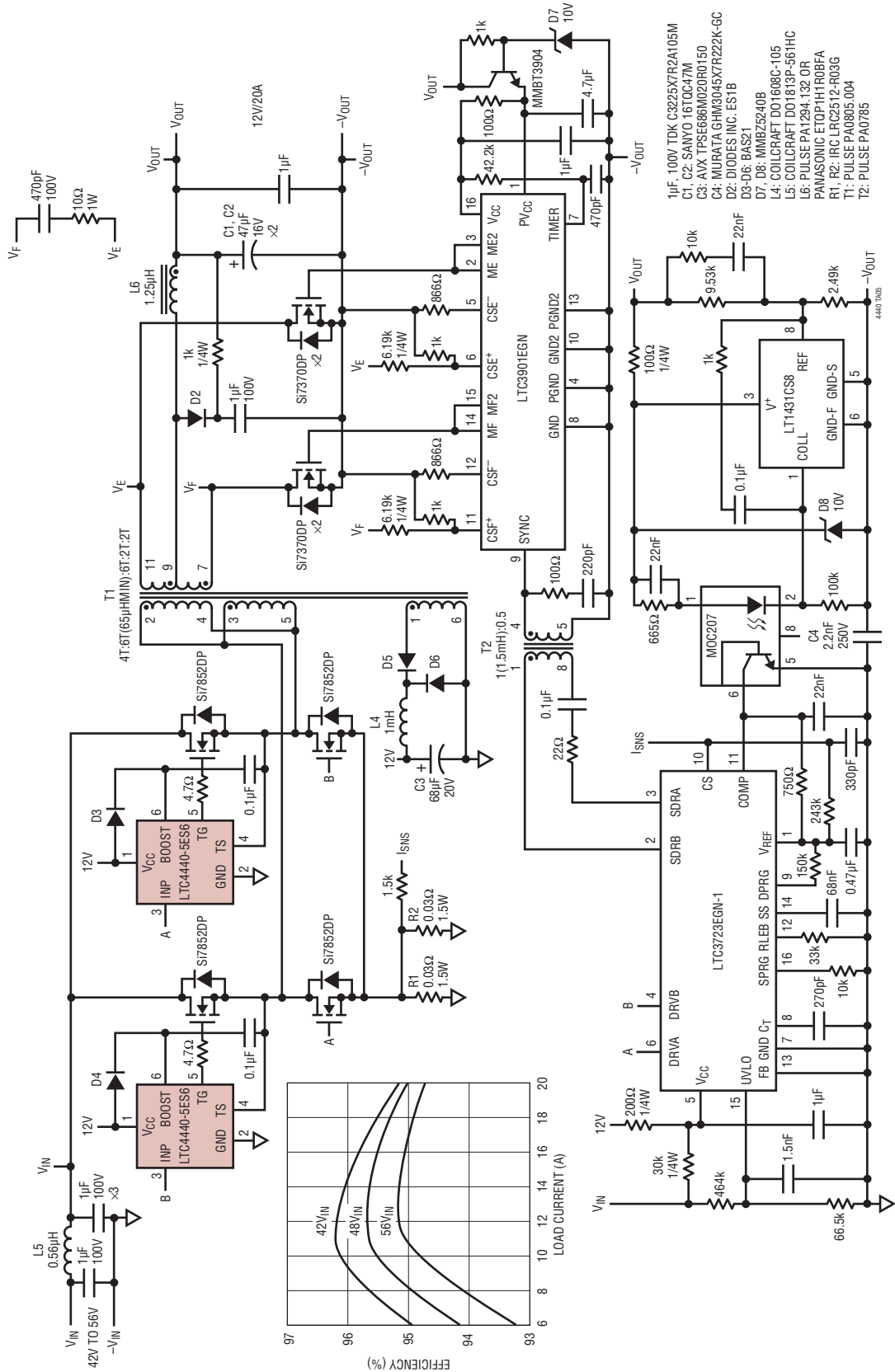
- Mount the bypass capacitors as close as possible between the V_{CC} and GND pins and the BOOST and TS pins. The leads should be shortened as much as possible to reduce lead inductance.
- Use a low inductance, low impedance ground plane to reduce any ground drop and stray capacitance. Remember that the LTC4440-5 switches >2A peak currents and any significant ground drop will degrade signal integrity.
- Plan the power/ground routing carefully. Know where the large load switching current is coming from and going to. Maintain separate ground return paths for the input pin and the output power stage.
- Keep the copper trace between the driver output pin and the load short and wide.
- When using the MS8E package, be sure to solder the exposed pad on the back side of the LTC4440-5 package to the board. Correctly soldered to a 2500mm² double-sided 1oz copper board, the LTC4440-5 has a thermal resistance of approximately 40°C/W. Failure to make good thermal contact between the exposed back side and the copper board will result in thermal resistances far greater than 40°C/W.

TYPICAL APPLICATIONS

LTC3722/LTC4440-5 420W 36V-60V_{IN} to 12V/35A Isolated Full-Bridge Supply

TYPICAL APPLICATIONS

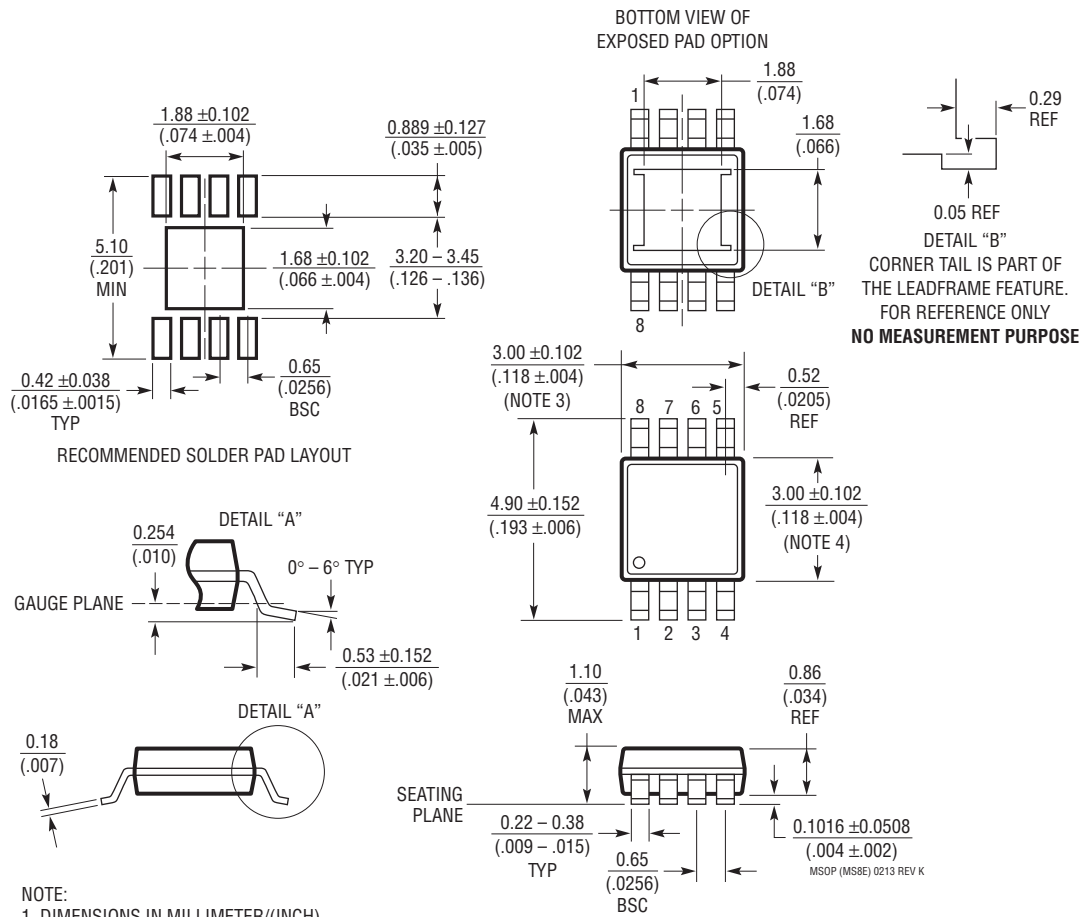
LTC3723-1 240W 42-56V_{IN} to 12V/20A Isolated 1/4Brick (2.3" × 1.45")



PACKAGE DESCRIPTION

Please refer to <http://www.linear.com/designtools/packaging/> for the most recent package drawings.

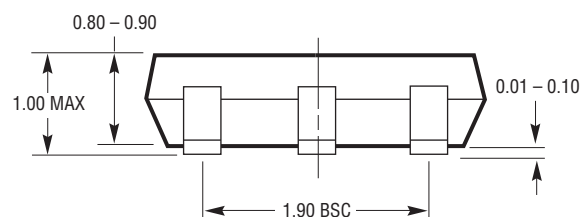
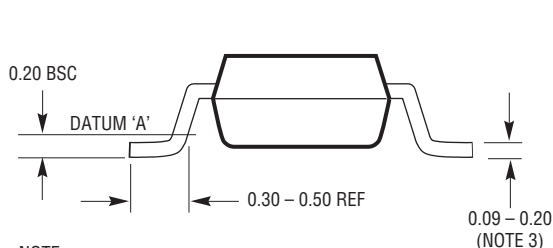
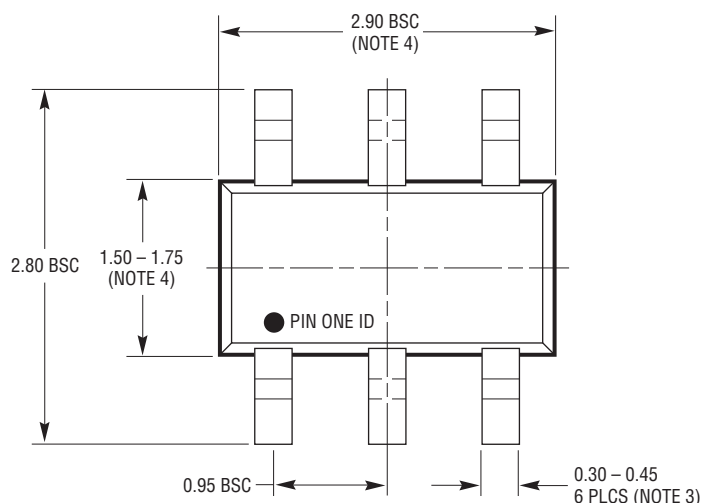
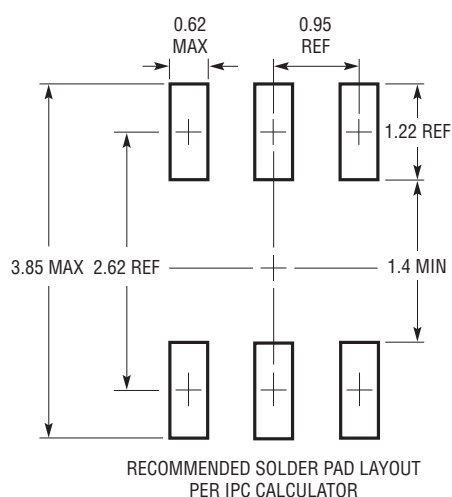
MS8E Package 8-Lead Plastic MSOP, Exposed Die Pad (Reference LTC DWG # 05-08-1662 Rev K)



PACKAGE DESCRIPTION

Please refer to <http://www.linear.com/designtools/packaging/> for the most recent package drawings.

S6 Package
6-Lead Plastic TSOT-23
 (Reference LTC DWG # 05-08-1636)



NOTE:

1. DIMENSIONS ARE IN MILLIMETERS
2. DRAWING NOT TO SCALE
3. DIMENSIONS ARE INCLUSIVE OF PLATING
4. DIMENSIONS ARE EXCLUSIVE OF MOLD FLASH AND METAL BURR
5. MOLD FLASH SHALL NOT EXCEED 0.254mm
6. JEDEC PACKAGE REFERENCE IS MO-193

S6 TSOT-23 0302

REVISION HISTORY (Revision history begins at Rev B)

REV	DATE	DESCRIPTION	PAGE NUMBER
B	1013	Added comparison table	1

TYPICAL APPLICATION

240W 42V-56V_{IN} to Unregulated 12V Half-Bridge Converter

